

WHAT IS CLAIMED IS:

1. A mounting structure of a semiconductor device mounted on a mounting substrate, comprising:

5 a semiconductor device having a bump electrode which has an acute tip on top,
a mounting substrate on which said semiconductor device is mounted, and
a conductor pattern formed on said mounting substrate, wherein said acute tip is
gradually depressed on said conductor pattern of said mounting substrate.

10 2. A mounting structure of a semiconductor device mounted on a mounting substrate
as claimed in Claim 1, wherein said acute tip of the bump electrode is treated with a
leveling process as to form a small flat surface before depressed on said conductor pattern
of the mounting substrate.

15 3. A mounting structure of a semiconductor device mounted on a mounting substrate
as claimed in Claim 2, wherein heat is added to said bump electrode of the semiconductor
device so that said bump electrode is transformed during depression of the bump electrode
to the conductor pattern of the mounting substrate.

20 4. A mounting structure of a semiconductor device mounted on a mounting substrate
as claimed in Claim 3, wherein said mounting substrate is a printed circuit board and said
bump electrode is depressed on the conductor pattern formed on the printed circuit board.

25 5. A mounting structure of a semiconductor device mounted on a mounting substrate
as claimed in Claim 4, wherein said semiconductor device has an electrode pad and said
bump electrode is formed on this electrode.

30 6. A mounting structure of a semiconductor device mounted on a mounting substrate
as claimed in Claim 1, wherein said acute tip of the bump electrode has a shape of a cone.

7. A process of mounting a semiconductor device on a mounting substrate, said
process comprising the steps of,